

Soldered SAM data sheet SAM-λ-A-τ-4.0-25.0s-c or 4.0-25.0s-e

GaAs chip area standard: 4.0 mm x 4.0 mm
 optional: other dimensions on request

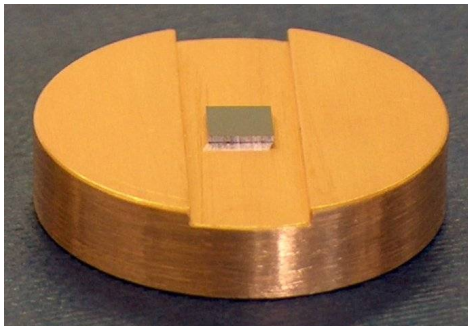
Chip thickness standard: 450 μm

Front side protection the SAM is protected with a dielectric front layer.

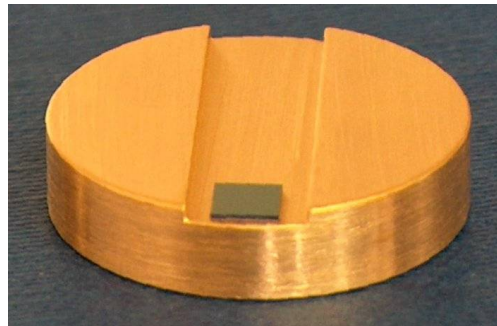
The SAM chip is soldered on a gold plated Cu-cylinder with 25.0 mm Ø using a Sn/Bi solder. The solder ensures low thermal resistance between the SAM and the heat sink

- The **standard** position of the SAM is at the center of the mount → x = 4.0-25.0s-c.
- **Optional** the SAM can be mounted at the edge of the mount without extra charges
 → x = 4.0-25.0s-e.

Center mounted SAM



Edge mounted SAM



Mount

Cu-cylinder, Ø = 25.0 mm
 l = 6.0 mm

